


Date: 4/25/2021

Material Number: EFR32BG21A010F512IM32-B

Pkg Config.: PK1526

Detailed Device Composition 									
No.	Homogeneous Material	Material Weight (mg)	Material Content	CAS Number	Material Weight (%)	Material Weight (mg)	ppm of Material	Wt % of Total Unit	ppm of Total Unit
1	Die Attach Epoxy	0.58	Acrylates	Proprietary	4.000	0.023	40000	0.0461	461
			Acrylic Resin	Proprietary	9.000	0.052	90000	0.1036	1036
			Additive	Proprietary	1.500	0.009	15000	0.0173	173
			Butadiene Copolymer	Proprietary	1.000	0.006	10000	0.0115	115
			Epoxy Resin (Proprietary)	Proprietary	2.000	0.012	20000	0.0230	230
			Peroxide	Proprietary	0.500	0.003	5000	0.0058	58
			Polybutadiene Derivative	Proprietary	5.000	0.029	50000	0.0576	576
			Silver	7440-22-4	77.000	0.444	770000	0.8867	8867
2	Bond Wire	0.14	Copper	7440-50-8	96.000	0.136	960000	0.2721	2721
			Gold	7440-57-5	1.000	0.001	10000	0.0028	28
			Palladium	7440-05-3	3.000	0.004	30000	0.0085	85
3	Mold Compound	17.92	Carbon Black	1333-86-4	0.300	0.054	3000	0.1073	1073
			Epoxy Resin A	Proprietary	3.000	0.538	30000	1.0729	10729
			Epoxy Resin B	126-80-7	3.000	0.538	30000	1.0729	10729
			Metal Hydroxide	Proprietary	1.500	0.269	15000	0.5365	5365
			Phenol Resin (Proprietary)	Proprietary	5.000	0.896	50000	1.7882	17882
			Silica	7631-86-9	87.200	15.627	872000	31.1869	311869
4	Plating - External	1.09	Tin	7440-31-5	100.000	1.092	1000000	2.1793	21793
5	Leadframe	27.70	Copper	7440-50-8	91.323	25.296	913230	50.4839	504839
			Iron	7439-89-6	2.186	0.606	21860	1.2084	12084
			Lead	7439-92-1	0.005	0.001	50	0.0028	28
			Phosphorous	7723-14-0	0.073	0.020	730	0.0404	404
			Silver	7440-22-4	6.300	1.745	63000	3.4827	34827
			Zinc	7440-66-6	0.113	0.031	1130	0.0625	625
6	Die	2.68	Silicon	7440-21-3	99.800	2.671	998000	5.3298	53298
			Silicon Dioxide	60676-86-0	0.200	0.005	2000	0.0107	107
	Total Unit Weight =	50.11				50.11		100.0000	1000000